

AMENDMENTS TO THE CLAIMS

Please amend the Claims as follows. Insertions are shown underlined while deletions are ~~struck through~~. Please cancel Claims 6, 7, and 9-14.

1 (currently amended): A dicing/die-bonding film comprising:

a supporting base material,

a pressure-sensitive adhesive layer formed on ~~at~~ the supporting base material, ~~and~~

a die-bonding adhesive layer formed on the pressure-sensitive adhesive layer, said die-bonding adhesive layer being comprised of a work-attaching portion on which a work is to be attached and a no-work-attaching portion other than the work-attaching portion,

~~wherein an interface between the pressure sensitive adhesive layer and the die-bonding adhesive layer comprises an interface (A) formed between corresponding to the work-attaching region-portion in of the die-bonding adhesive layer and a portion (a) of the pressure-sensitive adhesive layer in contact with the work-attaching portion, and~~

an interface (B) formed between corresponding to a part or a whole of the no-work-attaching portion of the die-bonding adhesive layer and a portion (b) of the pressure-sensitive adhesive layer in contact with the part or the whole of the no-work-attaching portion ~~a region other than the work-attaching region, and~~

wherein releasability between the pressure-sensitive adhesive layer and the die-bonding adhesive layer at the interface (A) is higher than the releasability at the interface (B).

2 (currently amended): The dicing/die-bonding film according to claim 1, wherein adhesion of the pressure-sensitive adhesive layer to the die-bonding adhesive layer is different between ~~a region~~ the portion (a) corresponding to the work-attaching region in the die-bonding adhesive layer and ~~a region~~ the portion (b) corresponding to a part or the whole of the other region, and satisfies the relationship:

the adhesion of the ~~region-portion~~ (a) is lower than the adhesion of ~~region-portion~~ (b).

3 (currently amended): The dicing/die-bonding film according to claim 1, wherein adhesion of the work-attaching ~~region-portion in of~~ the die-bonding adhesive layer to ~~the~~ work and to the ~~region-portion~~ (a) satisfies the relationship:

the adhesion to the work is higher than the adhesion to the region (a).

4 (currently amended): The dicing/die-bonding film according to claim 1, wherein ~~thea~~ part of the ~~region other than the~~ no-work-attaching region-portion ~~inof~~ of the die-bonding adhesive layer is a dicing ring-attaching ~~regionportion~~ to which a dicing ring is to be attached.

5 (currently amended): The dicing/die-bonding film according to claim 4, wherein adhesion of the dicing ring-attaching ~~region-portion inof~~ of the die-bonding adhesive layer to ~~athe~~ dicing ring and to a ~~region-portion (b')~~ of the pressure-sensitive adhesive layer in contact with ~~corresponding to the dicing ring-attaching region-portion~~ satisfies the relationship:

the adhesion to the dicing ring is lower than the adhesion to the ~~region-portion (b')~~.

6-7 (canceled)

8 (currently amended): The dicing/die-bonding film according to claim 1, wherein the pressure-sensitive adhesive layer is made of a radiation-curing pressure-sensitive adhesive, and ~~the region-portion (a) corresponding to the work-attaching region-portion~~ is irradiated with radiations.

9-14 (canceled)